having the memory of a specified shape, said resin composition comprising:

an oligomer compound having at least one acryloyl group in the molecule and has a glass transition temperature of lower than 50°C after polymerization;

a low-molecular weight compound that has in its molecule one reactive double bond capable of polymerization with said oligomer compound and that has a glass transition temperature higher than at least 90°C after polymerization.

2. (Amended) A resin compound for use in a process for producing a cured film having the memory of a specified shape, said resin composition comprising:

an oligomer compound that has at least one acryloyl group in the molecule and that has a glass transition temperature lower than 50°C after polymerization; and

a urethane adduct of hydroxyethyl acrylate or hydoxyethyl methacrylate and a diisocyanate.

Please add the following new claims:

3. (New) A resin composition for use in a process for producing a cured film having the memory of a specified shape, said resin composition comprising:

an oligomer compound having at least one methacryloyl group in the molecule and has a glass transition temperature of lower than 50°C after polymerization; and

a low-molecular weight compound that has in its molecule one reactive double bond capable of polymerization with said oligomer compound and that has a glass transition temperature higher than at least 90°C after polymerization.

4. (New) The resin compound of Claim 1 further including a mixture of at least two

Subc'l cont.

low-molecular weight compounds that have in their molecule one reactive double bond capable of coplolymerization with said oligomer compound and that have a glass transition temperature higher than 90°C after polymerization.

5. (New) The resin compound of claim 3 further including a mixture of at least two low-molecular weight compounds that have in their molecule one reactive double bond capable of coplolymerization with said oligomer compound and that have a glass transition temperature higher than 90°C after polymerization.

6. (New) The resin compound of claim 4 wherein said process includes the steps of shaping a resin composition by applying it onto a shaped part, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films.

7. (New) The resin compound of claim 5, wherein said process includes the steps of shaping a resin composition by applying it onto a shaped part, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films.

8. (New) The resin composition of claim 4 wherein said which process comprises shaping a resin composition by placing it between films, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films.

9. (New) The resin composition of claim 5, wherein said which process comprises shaping a resin composition by placing it between films, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films.

10. (New) A resin composition for use in a process for producing a cured film having the memory of a specified shape, said resin composition comprising:

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an oligomer compound that has at least one methacryloyl group in the molecule and that has a glass transition temperature lower than 50°C after polymerization; and

a urethane adduct of hydroxyethyl acrylate or hydoxyethyl methacrylate and a diisocyanate.

11. (New) The resin composition of claim 2 further including an optional low molecular weigh compound that has in its molecule at least one double bond capable of copolymerization with said oligomer compound.

12. (New) The resin composition of claim 10 further including an optional low molecular weigh compound that has in its molecule at least one double bond capable of coploymerization with said oligomer compound.

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13. (New) The resin composition of claim 11 wherein said process includes the steps of shaping a resin composition by applying it onto a shaped part , curing said resin composition with electron beams, and removing the cured composition from the shaped part or films.

14. (New) The resin composition of claim 12 wherein said process includes the steps of shaping a resin composition by applying it onto a shaped part, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films.

15. (New) The resin composition of claim 11 wherein said process includes the steps of shaping a resin composition by placing it between films, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films.

16. (New) The resin compound of claim 12 wherein said process includes the steps of shaping a resin composition by placing it between films, curing said resin composition with